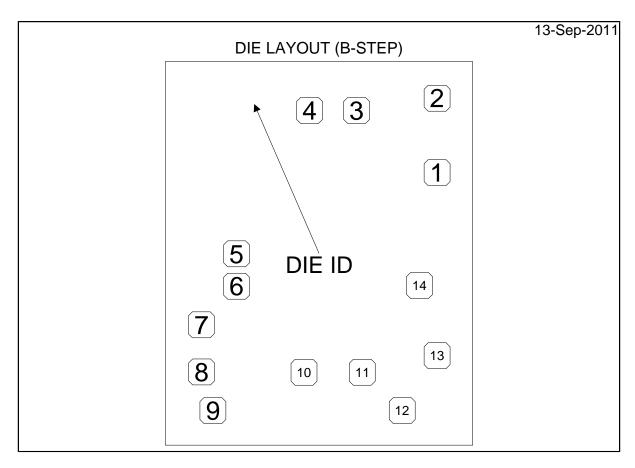


LMH6629 MDC Ultra-Low Noise, High-Speed Operational Amplifier with Shutdown



DIE/WAFER CHARACTERISTICS

DIE/WAI ER OFFICOTION							
Fabrication Attributes		General Die Information					
Physical Die	LMH6629B	Bond Pad Opening	68.00µm x 68.00µm				
Identification		Size (min)					
Die Step	В	Bond Pad Metalization	AL 0.5%CU				
Physical Attributes		Passivation	PECVDOX NITRIDE				
Wafer Diameter	203.2mm	Back Side Metal	BAREBACK				
Die Size (Drawn)	805.18µm x 1005.84µm	Back Side Connection	Floating				
	31.7mils x 39.6mils						
Thickness	254.0µm Nominal						
Min Pitch	123.38µm						
Note: All values are rounded to the nearest micron.							

Special Assembly Requirements:



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Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		Χ	Υ	Χ		Υ
PD	1	309	211	68	Х	68
FB	2	309	406	68	х	68
IN-	3	99	374	68	Х	68
IN+	4	-25	374	68	Х	68
NC	5	-216	-1	68	Х	68
NC	6	-216	-86	68	Х	68
V-	7	-308	-187	68	Х	68
V-	8	-308	-311	68	Х	68
COMP	9	-278	-412	68	Х	68
OUT	10	-39	-312	68	Х	68
NC	11	113	-312	68	х	68
V+	12	218	-412	68	Х	68
V+	13	309	-268	68	Х	68
NC	14	263	-84	68	Х	68



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